Code No: 126EN

R13

JAWAHARLAL NEHRU TECHNOLOGICAL UNIVERSITY HYDERABAD B. Tech III Year II Semester Examinations, October/November - 2016 VLSI DESIGN

		VLSI D				
an.	(Elect	ronics and Comm	unication Engi	neering)		
Time	: 3 hours	(×+ +×+x	*** ****	N	Max. Marks: 75	
Note	This question paper con	ntains two parts A	and B.	*	\$\tilde{\chi} \tilde{\chi} \til	****
	Part A is compulsory v consists of 5 Units. Ans 10 marks and may have	swer any one full	question from	r all questions in each unit. Each	Part A. Part B question carries	
	may maye					
***	R SR	PAR?	Γ - À:: ·::		(25 Marks)	* * * * * * * * * * * * * * * * * * *
1.a)	Define threehold					*
b)	Define threshold voltage	e of a MOS device	e.	1.0	[2]	
ç)	What are pull-ups and war. Explain about the contact	of cuts and approx	sistor pull-up a	nd its usage.	[3]	
d)	Represent the Stick diag	ram of a NMOS	inverter		[2]	
e)	Write about the clocked	CMOS logic and	lite usage	*******	[3]	1.,017
f)	Explain about the Wirin	g capacitance and	d its usage.		[2]	
g)	Mention about SRAM a	nd its usage.	a its need.		[2]	
h)	Describe about the Seria	l Access Memor	ies.		[3]	
i):::	Explain about the princi			*****		,,,,,,,,,,,
j).: :	Explain about test Princi	iples used for test	ting	* (*** * **** * * * * * * * * * * * * *	[2] [3]	* * * * * * * * * * * * * * * * * * *
		PART	ם י			
		IANI	Б		(50 Marks)	
					(001,201,15)	
2.a)	Write about BiCMOS fa	brication in a n-v	vell process wi	th a diägräm.	*** ****	*** *** ;
b) :	Distinguish between Bip	olar and CMOS	devices techno	logies in brief.	[5+5]	,
2 \	26	OF	-			
3.a)	Mention about the BICM	IOS Inverters and	d alternative B	ICMOS Inverter	S.	*
b)	Determine the pull-up to	pull down ratio	for NMOS inv	erter driven by a	nother NMOS	
**** ***	Inverter.	< > * < × × × × × × × × × × × × × × × × × ×	*x.x.		[5+5]	*** ****
4.a)	Discuss about the stick d	ingrams and their	, , , , , , , , , , , , , , , , , , ,	*****	1 *** * * * *	
b)	Discuss about the stick d Draw the stick diagram of	of p well CMOS	r correspondin	g mask layout ex	amples.	
٠,	Dian the stick diagram c	OR		tpiain the process	5. [5+5]	
5.a)	Explain about the 2 µm (with a layout ex	amnle	
b)	Draw and explain the lay	out for CMOS 2	input NAND	gate	[5+5]	
****	******	* * * * * * * * * * * * * * * * * * * *	1	Saco	···· ··· ··· ··· ··· ·· ·· ·· · · · ·	
6.	Discuss about the logics	implemented in g	gate level desig	gn and explain th	e switch logic	*******
	implementation for a four	r way multiplexe	r.		[10]	
	_	OR	=		, <u>.</u>	
7.a)	Describe about the metho	ods for driving lan	rge capacitive	loads.		
b.).	Describe about the choice	of fan – in and	fan - out selec	tion in gate level	design[5+5]	****
* * . * .	* * * * ×	**** ***	* * * * * * * * * * * * * * * * * * *	******	*** ***	

	o) Exp	lain the working	principle of Rip	ple carry adder us OR	I by a two-phase sing Transmission	clock. [5+5]	1 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0
7	10.a) Expl	w the circuit diag	gram of four trans logic configurable lifferent Paramete	blication and its of sistor DRAM cells and sistor DRAM cells are block Architecters influencing look	with storage noc	les. [5+5]	SR
	a) Cl	ain the following hip level Test Te estability and pra	g in detail. chniques actices.			[5+5]	
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					3Ē	BR	
	ÜR			ÖK			SR
	SR ,			SF.			
	SR	8R	SR			SR	5